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Sheet: 1 of 1

REV: 7-8 37 C.F.R. 1.98 37 OCT 14 1993	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY DOCKET NO. 71-579.2	SERIAL NUMBER 0812267712
		APPLICANT Tuttle, et al.	D. Barby
		FILING DATE 10/14/93	GROUP 1304 7/16/94
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U.S. PATENT DOCUMENTS

EXMNR INITL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	
AA						
AB						
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AD						
AE						
AF						
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AH						
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EXMNR INITL		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
AL								
AM								
AN								
AO								

OTHER ART

(include Author, Title, Date, Pertinent Pages, Publisher)

<i>PR</i>	AP		Keith Casson and Kelly Habeck, "High Temperature Packaging: Flip Chip on Flexible Laminate," January 1992, Surface Mount Technology pp 19-20.
<i>PR</i>	AQ		R. Wayne Johnson, "Polymer Thick Films: Technology and Materials," Circuits Manufacturing July 1982.
<i>PR</i>	AR		Ken Gilleo, "Using SM Devices On Flexible Circuitry," March 1986, Electri-onics, pp 20-23.

Examiner <i>Paul Riordan</i>	DATE CONSIDERED <i>1/6/95</i>
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EXAMINER: Initial if the reference was considered, whether or not the citation is in conformance with MPEP 609. Draw a line through citation if not considered. Include a copy of this form with the next communication to the Applicant.